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110403

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Mail Stop Patent Application

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

17510 U.S. PTO
10/701061
11/04/03

Transmitted herewith for filing under 37 CFR 1.53(b) are the specification and claims of the nonprovisional patent application of:

Hitoshi Arita and Akio Kojima
Inventor(s)

SOLDER ALLOY MATERIAL LAYER COMPOSITION, ELECTROCONDUCTIVE AND ADHESIVE
COMPOSITION, FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL TRANSFERRING SHEET,
BUMP AND BUMP FORMING PROCESS, AND SEMICONDUCTOR DEVICE

Title of Invention

APPLICATION ELEMENTS ENCLOSED:

1. X Specification, total pages 190 including:
 - a. 21 pages of claims (54 claims)
 - b. 1 page(s) Abstract
2. X 13 sheets of informal X formal drawings (Figs. 1-23)
3. Oath or declaration of Applicant(s) (5 total pages)
 - a. Newly executed (original)
 - b. Unexecuted
 - c. Copy from a prior application (37 CFR 1.63(d))
(for continuation/divisional with Item 14 completed)
4. Deletion of Inventor(s)
Signed statement attached deleting inventor(s) named in the prior application, see 37 CFR 1.63(d)(2) and 1.33(b)
5. Incorporation By Reference
The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied in item 3b is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
6. Microfiche Computer Program (Appendix)

APPLICATION PARTS ENCLOSED:

7. An assignment (cover sheet & document(s))
8. 37 CFR 3.73(b) Statement (when there is an assignee)
9. Power of Attorney
 - a. Newly executed (original)
 - b. Unexecuted
 - c. Copy from a prior application

- 10.____ Information Disclosure Statement (IDS) and PTO-1449
____ Copies of IDS Citations
- 11.____ A Preliminary Amendment
12. X Return Receipt Postcard (MPEP 503)
- 13.____ Applicant(s) hereby establish small entity status under 37 C.F.R. §1.9 and §1.27
- 14.____ If a Continuing Application, *check the appropriate box and supply the requisite information:*

☐ Continuation of prior application No.: _____ filed _____

☐ Divisional of prior application No.: _____ filed _____

☐ Continuation-in-part (CIP) of prior application No.: _____ filed _____

- 15.____ Amend the specification by inserting before the first line of page one: --This is a ____ continuation ____ divisional of application Serial No. _____ filed ____.--
16. X Applicant hereby claim priority under 35 U.S.C. §119..
X Certified copies of priority applications No. 2002-322678, filed on November 6, 2002, in Japan, No. 2002-340384, filed on November 25, 2002, in Japan and No. 2002-342329, filed on November 26, 2002, in Japan are enclosed herewith.
17. X Other (identify) Express Mail Letter of Transmittal bearing Label No. EV 325707583 dated November 4, 2003


The filing fee is calculated as follows:

CLAIMS AS FILED, LESS ANY CLAIMS CANCELLED BY AMENDMENT

| | | | | | Rate | | Fee | |
|---|-----------------|---|------------------|---|-----------------|-----------------|-----------------|-----------------|
| | Number Filed | | Number Extra* | | Small Entity | Other Entity | Small Entity | Other Entity |
| Total Claims | 54 - 20 | = | 34 | X | \$ 9 | \$ 18 | \$ 0 | \$ 612.00 |
| Indep. Claims | 9 - 3 | = | 6 | X | \$ 43 | \$ 86 | \$ 0 | \$ 516.00 |
| Multiple Dependent Claims Presented: Yes____ No <u>x</u> | | | | | \$140 | \$280 | \$ 0 | \$ 0.00 |
| If the difference in column 1 is less than zero, enter "0" in column 2 | | | | | Basic Fee | | \$385.00 | \$ 770.00 |
| | | | | | Total Fee | | \$ | \$1,898.00 |

- CORRESPONDENCE ADDRESS:

Respectfully submitted,


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Hitoshi Arita and Akio Kojima
Serial No. : Not Yet Known
Date Filed : Herewith
Priority Date : November 6, 2002
For : SOLDER ALLOY MATERIAL LAYER COMPOSITION,
ELECTROCONDUCTIVE AND ADHESIVE COMPOSITION,
FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL
TRANSFERRING SHEET, BUMP AND BUMP FORMING
PROCESS, AND SEMICONDUCTOR DEVICE

Mail Stop Patent Application

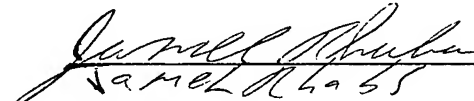
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

EXPRESS MAIL LETTER OF TRANSMITTAL

Express Mail mailing label number: EV 325707583 US
Date of Deposit: November 4, 2003

I hereby certify that the above-identified application of Hitoshi Arita and Akio Kojima for SOLDER ALLOY MATERIAL LAYER COMPOSITION, ELECTROCONDUCTIVE AND ADHESIVE COMPOSITION, FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL TRANSFERRING SHEET, BUMP AND BUMP FORMING PROCESS, AND SEMICONDUCTOR DEVICE, including application transmittal in triplicate, Specification (190 pages), Claims (1-54, 21 pages), Abstract (1 page), 13 drawing sheets (Figs. 1-23), Certified copies of JP 2002-322678, JP2002-340384, and JP2002-342329, a check in the Amount of \$1,898.00 for Filing Fee, and Return Postcard., is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and is addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450.



James H. Glass

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Depositing Express Mail Material

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